



ISO 9001 Registered Quality System.
Burlington, Ontario, Canada QMI File # 004008

Black Epoxy Encapsulating & Potting Compound 832B Technical Data Sheet

832B

Description

The 832B Black Epoxy Encapsulating and Potting Compound is an electric grade epoxy. It is simple to mix and easy to use. This two parts black epoxy provides great insulation and protection value.

It protects against static discharges, shocks, vibrations, and mechanical impacts. It insulates against heat and conductivity. It is extremely resistant to environmental humidity, salt water, and many harsh chemicals.

Applications & Usages

The 832B epoxy is used to pot or encapsulate printed circuit assemblies in protective blocks. The cured epoxy improves reliability, operational range, and lengthens the life of electrical and electronic parts. It also helps hide and restrict access to proprietary design elements.

Its primary applications are in the automobile, marine, aerospace, aviation, communication, instrumentation, and industrial control equipment.

Benefits

- **Extreme impact resistance** (contains a form of nylon)
- **Extreme resistance to water and humidity** allowing submersion if needed
- **Strong chemical resistance** to brine, acids, bases, and aliphatic hydrocarbons
- **Opaque and extremely difficult to remove material** providing high security for proprietary designs
- **Good protection of electronics against** corrosion, fungus, thermal shock, and static discharges
- **Easy 2A:1B mix ratio** compatible with most dispensing equipment
- **Negligible Volatile Organic Content (VOC)**
- **RoHS Compliant**

Curing & Work Schedule^a

<i>Properties</i>	<i>Value</i>
Working Life*	60 minute
Shelf Life	≥3 year
Full Cure (at 20 °C [68 °F])	24 hour
Full Cure (at 65 °C [149 °F])	60 minute
Full Cure (at 80 °C [176 °F])	45 minute
Full Cure (at 100 °C [212 °F])	35 minute
Storage Temperature of Unmixed Parts	16 to 27 °C [60 to 80 °F]

a) Working life assumes room temperature.
A 10 °C increase can decrease the pot life by half.

Temperature Service Ranges

<i>Properties</i>	<i>Value</i>
Constant Service Temp.	-30 °C to 140 °C [-22 to 284 °F]
Service Temperature ^b	<-30 +145 °C [<-22 +294 °F]

b) The service temperature provides temperature extremes that can be withstood for short periods of time only.



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Principal Components

Name	CAS Number
Part A: Bis-A Epoxide Resin	25068-38-6
Alkyl Glycidyl Ether Epoxide Resin	68609-97-2
Part B: Curing Polyamide	68082-29-1
Curing Aliphatic amine	112-24-3

Properties of Cured 832B

<i>Physical Properties</i>	<i>Method</i>	<i>Value^a</i>
Color	Visual	Black
Density (at 26 °C)	ASTM D 792	1.12 g/cm ³
Hardness	(Shore D durometer)	80D to 82D
Tensile Strength	ASTM D 638	56.9 N/mm ² [8,250 lb/in ²]
Elongation	"	3.3%
Lap Shear Strength	ASTM D 1002	4.2 N/mm ² [606 lb/in ²]
Izod Impact ^b	ASTM D 256	0.932 kJ/m ² [0.443 ft·lb/in]
Compression Strength	ASTM D 695	155 N/mm ² [22,400 lb/in ²]
Modulus	"	2590 N/mm ² [375,000 lb/in ²]
Flexural Strength	ASTM D 790	113.76 N/mm ² [16,500 lb/in ²]
Modulus	"	2940 N/mm ² [427,000 lb/in ²]
<i>Electric Properties</i>		
Breakdown Voltage	ASTM D 149	51.9 kV @ avg. of 2.79 mm
Dielectric Strength	"	472 V/mil [18.6 kV/mm]
Volume Resistivity	ASTM D 257	5.3 x10 ¹² Ω·cm
Surface Resistivity ^c	"	3.1 x10 ¹⁰ Ω
Comparative Tracking Index	ASTM D 3628	Not established
Dielectric Dissipation & Constant		<i>dissipation, D</i> <i>constant, k'</i>
@60 Hz	ASTM D 150-98	0.007 3.90
@1 kHz	"	0.008 2.95
@10 kHz	"	0.013 2.89
@100 kHz	"	0.018 2.83
@1 MHz	"	0.017 2.77

a) N/mm² = mPa; lb/in² = psi;

b) Sample thickness 0.259"

c) The surface (sheet) resistivity unit is commonly referred to as "Ohm per square"



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<i>Thermal Properties</i>	<i>Method</i>	<i>Value</i>
Coefficient of Thermal Expansion (CTE) ^a	ASTM E 831	104 ppm/°C
Glass Transition Temperature (T _g)	ASTM D 3418	Not established
Heat Deflection Temperature (HDT) ^b	ASTM D 648	46.638 °C [115.95 °F]

a) ppm/°C = in/in/°C × 10⁻⁶ = unit/unit/°C × 10⁻⁶

b) HDT under a 1820 kPa [264 lb/in²] load

Properties of Uncured 832B

<i>Physical Property</i>	<i>Mixture (2A:1B)</i>	
Color	Black	
Viscosity ^a at 20 °C [73 °F]	3,300 cP [3.3 Pa·s]	
Density	1.058 g/mL	
Mix Ratio by volume (A:B)	2.0:1.0	
Mix Ratio by weight (A:B)	2.3:1.0	
Solids Content (w/w)	99%	
<i>Physical Property</i>	<i>Part A</i>	<i>Part B</i>
Color	Black	Clear, Amber Tint
Viscosity* at 24°C [73 °F]	2,500 cP [2.5 Pa·s]	11,000 cP [11.0 Pa·s]
Density	1.127 g/mL	0.967 g/mL
Flash Point	154 °C [309 °F]	110 °C [230 °F]
Odor	Mild	Musty

a) Brookfield viscometer at 50 RPM with spindle #4



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Compatibility

Adhesion—As seen in the substrate adhesion table, the 832B epoxy adheres to most materials found on printed circuit assemblies; however, it is not compatible with contaminants like water, oil, and greasy flux residues that may affect adhesion. If contamination is present, clean the printed circuit assembly with electronic cleaner such as MG Chemicals 4050 Safety Wash, 406B Superwash, or 824 Isopropyl Alcohol.

Substrate Adhesion in Decreasing Order

<i>Physical Properties</i>	<i>Adhesion</i>
Aluminum	Stronger  Weaker
Steel	
Fiberglass	
Wood	
Glass	
Polycarbonate	
Acrylic	
Polypropylene	

Chemical Resistance—The chemical solvent resistance table presents the percent weight change over the indicated period. The results show low water absorption and a high chemical resistance to water and most ionic species. Softening and swelling occurs for aggressive organic solvents.

Chemical Solvent Resistance

<i>Physical Properties</i>	<i>Weight Change 3 days</i>	<i>Weight Change 45 days</i>
Water	< 0.0 %	< 1%
Hydrochloric Acid	< 0.0 %	< 1%
Isopropyl alcohol	0.3%	< 1%
Mineral spirits	0.3 %	0.3 %
Xylene	2 %	9 %
Ethyl Lactate	3 %	7 %
Iso hexanes	5 %	8%
Acetone	7 %	destroyed

Packaging and Supporting Products

Product Availability

- Cat. No. 832B-375ML (12 oz) / 832B-3L (0.8 gal) / 832B-60L (16 gal) Liquid

Storage

Store between 16 and 27 °C [60 and 80 °F] in dry area away from sunlight. Prolonged storage or storage at or near freezing temperatures can result in crystallization. If crystallization occurs, reconstitute the component to its original state by temporarily warming it to 50 to 60 °C [122 to 140 °F]. To ensure full homogeneity, stir thoroughly the warm component, reincorporating all settled material. Re-secure container lid and let cool down before use.

Health, Safety, and Environmental Awareness

Please see the 832B **Material Safety Data Sheet** (MSDS) parts A and B for more details on transportation, storage, handling and other security guidelines.

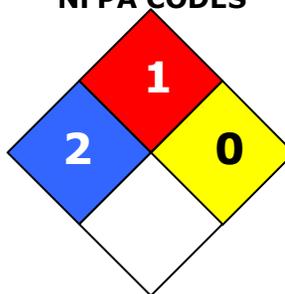
Environmental Impact: By EPA standards, the VOC is 2.0% (23 g/L) for part A and 12.1% (120 g/L) part B. The low vapor pressure of <0.001 kPa at 20 °C in part B is considered 0% VOC in Europe and Canada, and part B is a LVP-VOC exempted in California for consumer products. Note that the VOC in Part B is a reactive component. Reactive components become part of the cured epoxy solid and are therefore non-longer VOCs in their final form.

Part A

HMIS RATING

HEALTH:	2
FLAMMABILITY:	1
PHYSICAL HAZARD:	0
PERSONAL PROTECTION:	

NFPA CODES

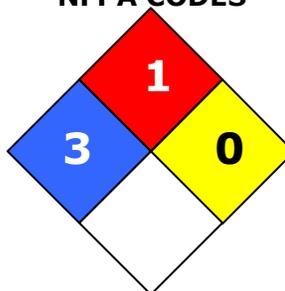


Part B

HMIS RATING

HEALTH:	3
FLAMMABILITY:	1
PHYSICAL HAZARD:	0
PERSONAL PROTECTION:	

NFPA CODES



Health and Safety: The 832 parts can ignite if the liquid is heated.

Wear safety glasses or goggles and disposable polyvinyl chloride, neoprene, or nitrile gloves while handling liquids. Part B in particular causes skin burns and may cause sensitization if exposed over a long period of time. The epoxy is black and will not wash off once cured: wear protective work clothing. Wash hands thoroughly after use or if skin contact occurs. Do not ingest.

While the product has low volatility and moderate odor, use in well-ventilated area.

The cured epoxy resin presents no known hazard.

Application Instructions

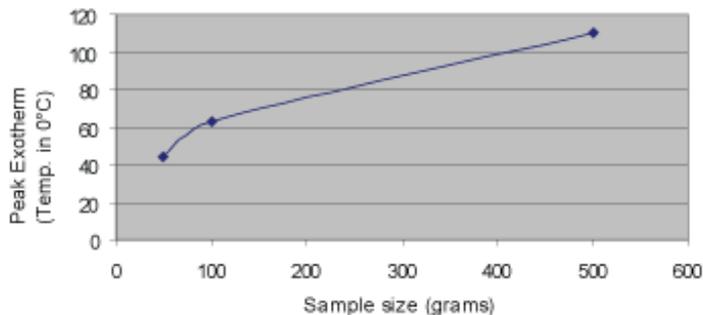
Follow the procedure below for best results. If you have little or no experience with the 832B epoxy, please follow the long instructions instead. The short instructions provided here are not suitable for first time users.

To prepare 2:1 (A:B) epoxy mixture

1. Scrape any settled material in the **Part A** container; and stir and fold material until homogenous.
2. Scrape any settled material in the **Part B** container; and stir and fold material until homogenous.
3. Measure **two** parts by volume of the pre-stirred **A**, and pour in the mixing container.
4. Measure **one** part by volume of the pre-stirred **B**, and slowly pour in the mixing container while stirring.
5. Put in a vacuum chamber, bring to 25 Hg/in pressure, and wait for 2 minutes to de-air.
—OR—
Let sit for 30 minutes to de-air.
6. If bubbles are present at top, use the mixing paddle to gently break them.
7. Pour mixture into the mold or container containing the components to be encapsulated.

ATTENTION! Mixing >500 g [0.4 L] of Part B at a time into A decreases working life and promotes flash cure. Use of epoxy mixing machines with static stirrer recommended for large volumes. Limit size of hand-mixed batches.

Peak Exotherm Temperature



To room temperature cure the 832B epoxy

Let stand for 24 hours.



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To heat cure the 832B epoxy

Put in oven at 65 °C [149 °F] for 60 minutes.

–OR–

Put in oven at 80 °C [176 °F] for 45 minutes.

–OR–

Put in oven at 100 °C [212 °F] for 35 minutes.

ATTENTION!

Due to exothermic reaction, heat cure temperatures should be at least 25% below the maximum temperature tolerated by the most fragile PCB component. For larger potting blocks, reduce heat cure temperature by greater margins.

Technical Support

Contact us regarding any questions, improvement suggestions, or problems with this product. Application notes, instructions, and FAQs are located at www.mgchemicals.com.

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Disclaimer

This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. M.G. Chemicals Ltd. does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.